

# PIN Diodes for RF Switching and Attenuating

## Technical Data

1N5719  
1N5767  
5082-3001  
5082-3039  
5082-3042/43  
5082-3077  
5082-3080/81  
5082-3188  
5082-3379

### Features

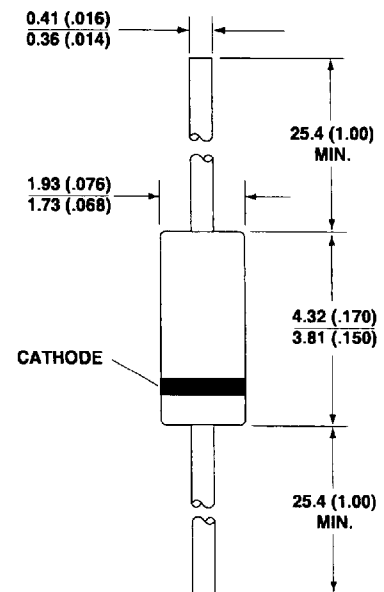
- Low Harmonic Distortion
- Large Dynamic Range
- Low Series Resistance
- Low Capacitance

### Description/Applications

These general purpose switching diodes are intended for low power switching applications such as RF duplexers, antenna switching matrices, digital phase shifters, and time multiplex filters. The 5082-3188 is optimized for VHF/UHF bandswitching.

The RF resistance of a PIN diode is a function of the current flowing in the diode. These current controlled resistors are specified for use in control applications such as variable RF attenuators, automatic gain control circuits, RF modulators, electrically tuned filters, analog phase shifters, and RF limiters.

Outline 15 diodes are available on tape and reel. The tape and reel specification is patterned after RS-296-D.



DIMENSIONS IN MILLIMETERS AND (INCHES).

Outline 15

### Maximum Ratings

Junction Operating and  
Storage Temperature Range ..... -65°C to +150°C  
Power Dissipation 25°C ..... 250 mW  
(Derate linearly to zero at 150°C)  
Peak Inverse Voltage (PIV) ..... same as V<sub>BR</sub>  
Maximum Soldering Temperature ..... 260°C for 5 sec

## Mechanical Specifications

The HP Outline 15 package has a glass hermetic seal with dumet leads. The lead finish is 95-5 tin-lead (SnPb) for all PIN diodes.

The leads on the Outline 15 package should be restricted so that the bend starts at least 1/16 inch (1.6 mm) from the glass body. Typical package inductance and capacitance are 2.5 nH and

0.13 pF, respectively. Marking is by digital coding with a cathode band.

## General Purpose Diodes

### Electrical Specifications at $T_A = 25^\circ\text{C}$

Part Number 5082-	Maximum Total Capacitance $C_T$ (pF)	Minimum Breakdown Voltage $V_{BR}$ (V)	Maximum Residual Series Resistance $R_S$ ( $\Omega$ )	Effective Carrier Lifetime $\tau$ (ns)	Reverse Recovery Time $t_{rr}$ (ns)
General Purpose Switching and Attenuating					
3001	0.25	200	1.0	100 (min.)	100 (typ.)
3039	0.25	150	1.25	100 (min.)	100 (typ.)
1N5719	0.3**	150	1.25	100 (min.)	100 (typ.)
3077	0.3	200	1.5	100 (min.)	100 (typ.)
Fast Switching					
3042	0.4*	70	1.0*	35 (typ.)*	5 (max.)
3043	0.4*	50	1.5*	35 (typ.)*	10 (max.)
Band Switching					
3188	1.0*	35	0.6**	70 (typ.)*	12 (typ.)
Test Conditions	$V_R = 50$ V $*V_R = 20$ V $**V_R = 100$ V $f = 1$ MHz	$V_R = V_{BR}$ Measure $I_R \leq 10$ mA	$I_F = 100$ mA $*I_F = 20$ mA $**I_F = 10$ mA $f = 100$ MHz	$I_F = 50$ mA $I_R = 250$ mA $*I_F = 10$ mA $*I_R = 6$ mA	$I_F = 20$ mA $V_R = 10$ V 90% Recovery

#### Notes:

Typical CW power switching capability for a shunt switch in a 50  $\Omega$  system is 2.5 W.

Part marking on glass package diodes, outline 15 is:

5082-xxxx

HPx

xxx

yww

For example, 1N5767 made in 1996 work week 35 would be marked:

HP5

767

635

## RF Current Controlled Resistor Diodes Electrical Specifications at $T_A = 25^\circ\text{C}$

Part Number	Effective Carrier Lifetime $t$ (ns)	Min. Breakdown Voltage $V_{BR}$ (V)	Max. Residual Series Resistance $R_S$ ( $\Omega$ )	Max. Total Capacitance $C_T$ (pF)	High Resistance Limit, $R_H$ (W)		Low Resistance Limit, $R_L$ (W)		Max. Difference in Resistance vs. Bias Slope, Dc
					Min.	Max.	Min.	Max.	
5082-3080	1300 (typ.)	100	2.5	0.4	1000			8**	
1N5767*	1300 (typ.)	100	2.5	0.4	1000			8**	
5082-3379	1300 (typ.)	50		0.4				8**	
5082-3081	2500 (typ.)	100	3.5	0.4	1500			8**	
Test Conditions	$I_F = 50$ mA $I_R = 250$ mA	$V_R = V_{BR}$ , Measure $I_R \leq 10$ mA	$I_F = 100$ mA $f = 100$ MHz	$V_R = 50$ V $f = 1$ MHz	$I_F = 0.01$ mA $f = 100$ MHz	$I_F = 1.0$ mA $I_F = 20$ mA** $f = 100$ MHz	Batch Matched at $I_F = 0.01$ mA and $1.0$ mA $f = 100$ MHz		

\*The 1N5767 has the additional specifications:  $\tau = 1.0$  msec minimum  
 $I_R = 1 \mu\text{A}$  maximum at  $V_R = 50$  V  
 $V_F = 1$  V maximum at  $I_F = 100$  mA.

### Typical Parameters at $T_A = 25^\circ\text{C}$ (unless otherwise noted)

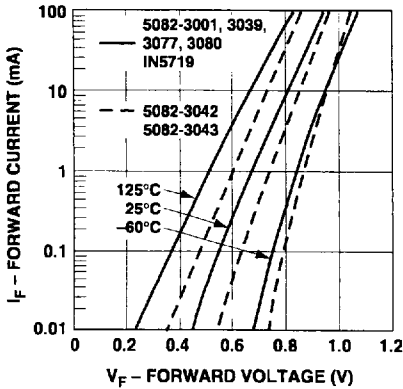


Figure 1. Forward Current vs. Forward Voltage.

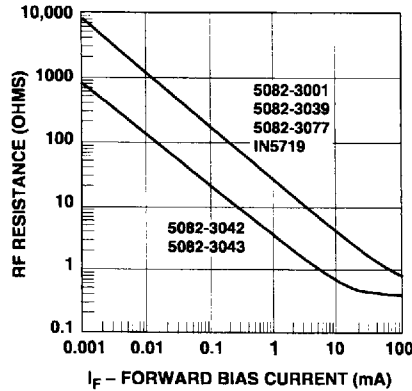


Figure 2. Typical RF Resistance vs. Forward Bias Current.

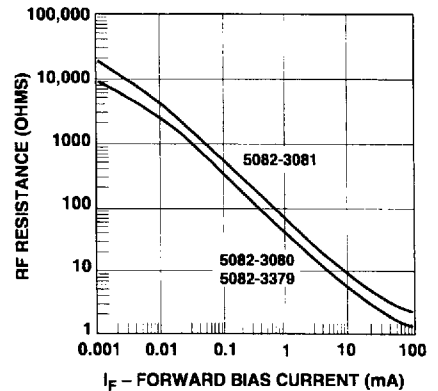
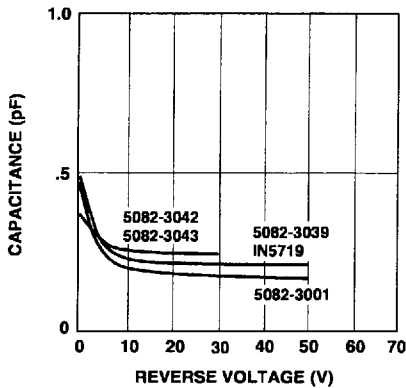
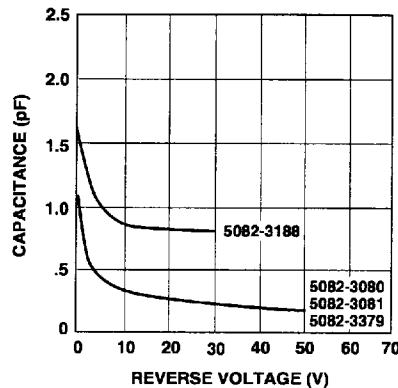


Figure 3. Typical RF Resistance vs. Forward Bias Current.

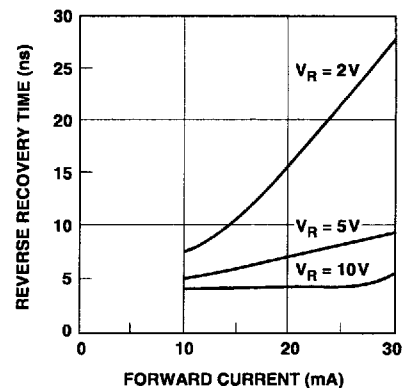
**Typical Parameters at  $T_A = 25^\circ\text{C}$  (cont.)**



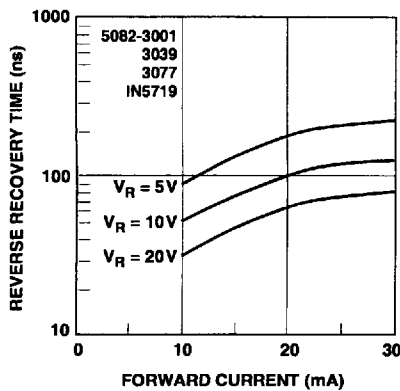
**Figure 4. Typical Capacitance vs. Reverse Voltage.**



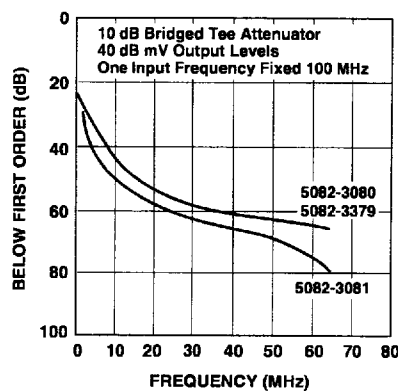
**Figure 5. Typical Capacitance vs. Reverse Voltage.**



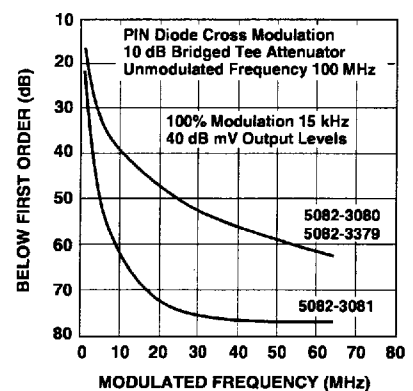
**Figure 6. Typical Reverse Recovery Time vs. Forward Current for Various Reverse Driving Voltages, 5082-3042, 3043.**



**Figure 7. Typical Reverse Recovery Time vs. Forward Current for Various Reverse Driving Voltages.**



**Figure 8. Typical Second Order Intermodulation Distortion.**



**Figure 9. Typical Cross Intermodulation Distortion.**

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